



GE Energy

Functional Testing Specification

Parts & Repair Services
Louisville, KY

LOU-GED-IS200DPWAG1A

Test Procedure for a IS200DPWAG1A

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PREPARED BY James Francis	REVIEWED BY	REVIEWED BY	QUALITY APPROVAL <i>Charlie Wade</i>
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LOU-GED-IS200DPWAG1A REV. A	g GE Energy Parts & Repair Services Louisville, KY	Page 2 of 3
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1. SCOPE

1.1 This is a functional testing procedure for an IS200DPWAG1A Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information.

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 85 DMM (or Equivalent)
1		Tenma Laboratory Power Supply

<p>LOU-GED-IS200DPWAG1A REV. A</p>	<p>g</p> <p>GE Energy Parts & Repair Services Louisville, KY</p>	<p>Page 3 of 3</p>
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6. TESTING PROCESS

6.1 Setup

6.1.1 Connect +28 VDC to P2-1 and 28 VDC Return to P2-2.

6.2 Testing Procedure

6.2.1 Check output voltage at P2, should be 28 VDC.

6.2.2 Check output voltage at P3 and P4, should be 13.5 VDC at both points.

6.2.3 Check output voltage at TB1-9 and TB1-10, should be 12 VDC.

6.2.4 Check output voltage at TB1-11 and TB1-12, should be 12 VDC.

6.2.5 Check output voltage at TB1-13 and TB1-14, should be 12 VDC.

6.2.6 Check output voltage at TB-1 (positive meter lead) and P2-2 (negative meter lead), should be 11.3 VDC.

6.2.7 Check output voltage at TB-3 (positive meter lead) and P2-2 (negative meter lead), should be 16 VDC.

6.2.8 Check output voltage at TB-5 (positive meter lead) and P2-2 (negative meter lead), should be 13.5 VDC.

6.2.9 Check remaining components and Traces with DMM.

6.2.10 Resistors:

6.2.10.1 Verify value as best as possible using a digital multimeter.

6.2.11 Diodes:

6.2.11.1 Replace all Glass bead diodes with new

6.2.11.2 Replace any fast recovery diodes with new

6.2.12 Use the diode setting on the DMM to check all remaining diodes

6.2.13 *****TEST COMPLETE**

7. NOTES

7.1 None at this time.

8. ATTACHMENTS

8.1 None at this time.